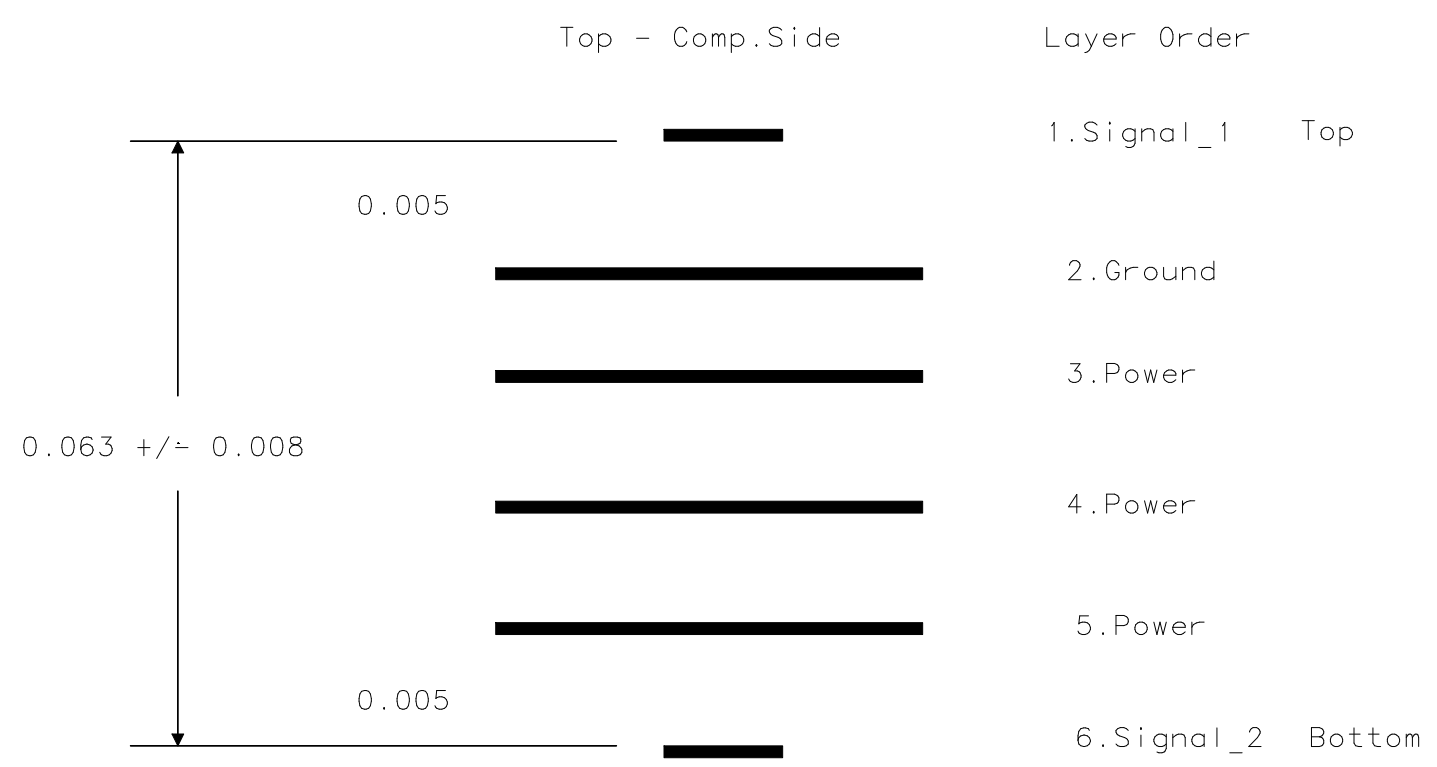
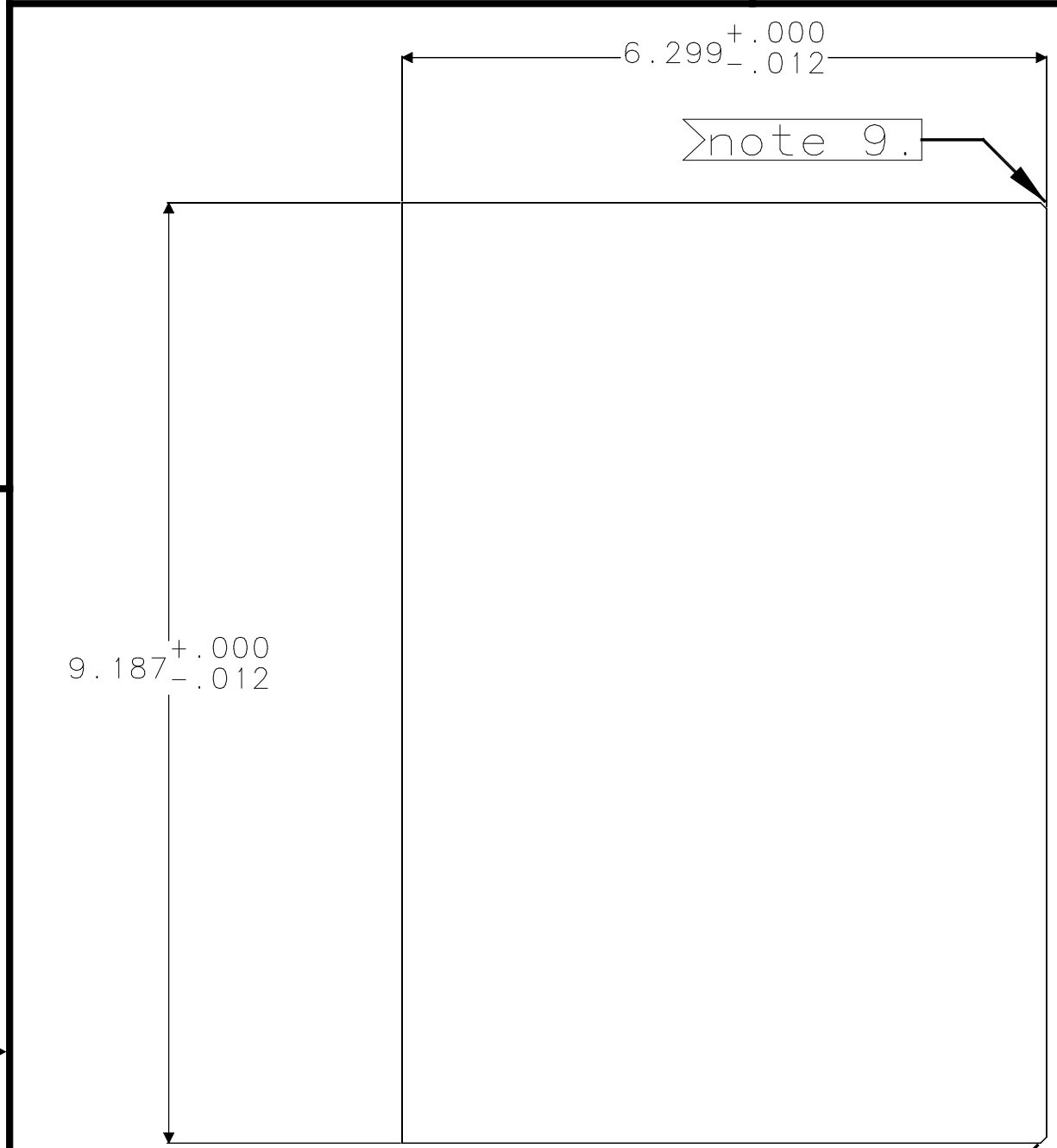


DWG. NO.	SH	REV.
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BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.014	897	YES	---	
⊞	.041	383	YES	---	
⊕	.057	8	YES	---	
⊞	.106	6	NO	---	
⊖	.15	3	NO	---	

Board Characteristics - 6 LAYER BOARD

0. All dimensions are given in inches unless specified otherwise.
1. Material FR4 - Tg > 170C
2. Minimum trace width and clearance: 0.005"
4. 1 oz copper for all power layers and for Signal\_1,2 (Top and Bottom)
5. Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.  
Apply Solder Mask over bare copper.
6. Board Thickness: 0.063 +/- 0.008
8. Silkscreen on Component and Solder Sides.
9. 45 degree chamfer.
10. FHS tolerances: +/- 0.003
11. Interlayer spacing as specified
12. Trace Impedance: Zc=50 Ohm +/- 10%

THIS SHEET IS COMPUTER GENERATED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS    DECIMALS    ANGLES .XX .XXX DO NOT SCALE DRAWING			CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP				
TREATMENT			APPROVALS	DATE	TITLE FTK Tester Specification Drawing				
FINISH			DRAWN M. Bogdan	6/27/12	SIZE B		FSCM NO.	DWG. NO. 2755	REV. B
SIMILAR TO			CHECKED M. Bogdan	6/27/12	SCALE 1/2		SHEET		